

# One Touch Access 200-SPI Module

One Touch.  
**One You.**  
NEXT Biometrics

## One Touch Access 200-SPI

The One Touch Access 200-SPI is a high quality fingerprint area sensor module designed for integration into custom application products including notebooks, tablets, time and attendance terminals, and card readers. It relies on the NEXT sensor chipset mounted on a small printed circuit board for seamless hardware integration. The module connects to the host system via a SPI interface using a flex cable.

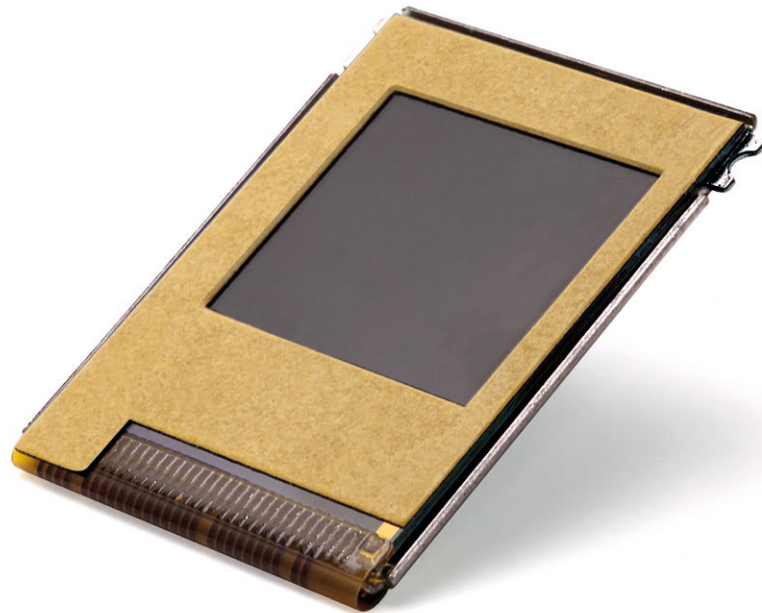
The sensor module works with the patented *NEXT Active Thermal™* principle. The sensor technology is tolerant against dirt, grease and varying environmental conditions. The large active area of the One Touch Access 200-SPI allows stable imaging, intuitive user operation and is ideally suited for mass market applications in need of both security and convenience.

The NEXT technology enables an economical production process that makes quality sensors available to price sensitive applications without compromising functionality or performance.

NEXT Biometrics offers a turnkey biometric subsystem by providing hardware drivers and a NEXT-certified partner algorithm for a variety of host platforms

### APPLICATION EXAMPLES:

- Notebook
- Tablets



## TECHNICAL SPECIFICATIONS

Sensor technology	<i>NEXT Active Thermal™</i> sensing (patented)
Total dimensions	20.9 x 27.39 x 2.97 mm <sup>3</sup> (including connector)
Active sensing area	11.9 x 11.9 mm <sup>2</sup>
Pixels	180 x 180
Resolution	385 ppi (pixel size 66 μm * 66 μm)
Gray scale levels	256
Image scan time	0.43 s
Power supply	3.3 V
Scan mode current draw	83 mA (typical)
Standby mode current draw	200 μA (maximum)
Logical interface	SPI 4-18 Mbps
Physical interface	12-pin FFC connector
ESD protection	±8 kV contact discharge, ±15 kV air discharge per IEC 61000-4-2
Mechanical durability	2 million touches @ 2.45 N
Scratch resistance	Durable lifetime coating, hardness ≥ 9H
Operating conditions	-10 °C to +60 °C at 95% RH (non-condensing)
Storage conditions	-20 °C to +70 °C at 95% RH (non-condensing)
Certifications	CE, FCC, RoHS, and WEEE



[www.nextbiometrics.com](http://www.nextbiometrics.com)

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